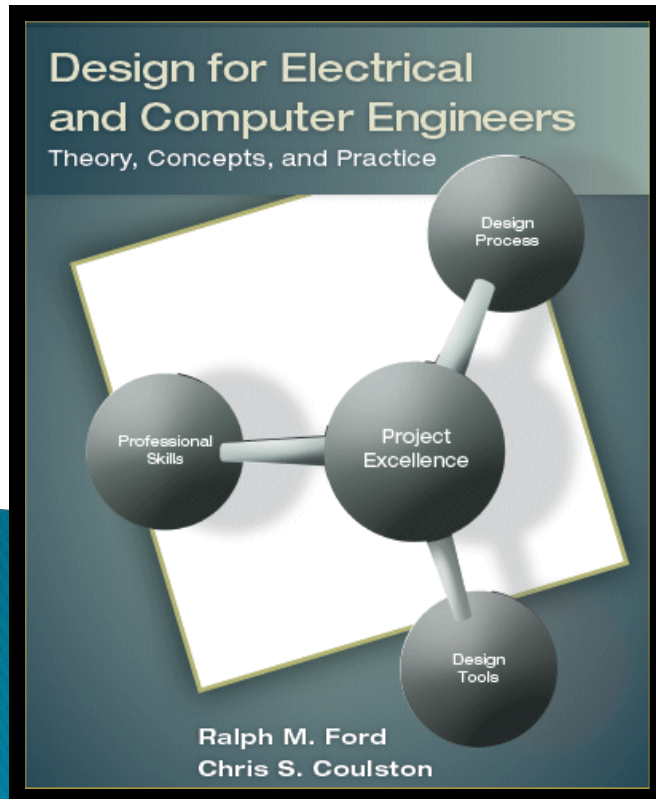


Chapter 5 – Functional Decomposition



Motivation – System Design

Team of engineers who build a system need:

- ▶ An abstraction of the system
- ▶ An unambiguous communication medium
- ▶ A way to describe the subsystems
 - Inputs
 - Outputs
 - Behavior
- ▶ Functional Decomposition
 - Function – transformation from inputs to outputs
 - Decomposition – reduce to constituent parts

Learning Objectives

- ▶ Understand the differences between **bottom-up** and **top-down design**.
- ▶ Know what **functional decomposition** is and how to apply it.
- ▶ Be able to apply functional decomposition to different problem domains.
- ▶ Understand the concept of **coupling** and **cohesion**, and how they impact design.

5.1 Bottom Up

- ▶ Given constituent parts
- ▶ Develop a working system
 - Build modules to accomplish specific tasks
 - Integrate modules together into working system
- ▶ For example
 - Given a power supply AND, OR and NOT gates.
 - Build a computer
- ▶ Pros
 - Leads to efficient subsystem. Lends itself to creativity.
- ▶ Cons
 - Complexity is difficult to manage
 - Little thought to designing reusable modules
 - Redesign cycles

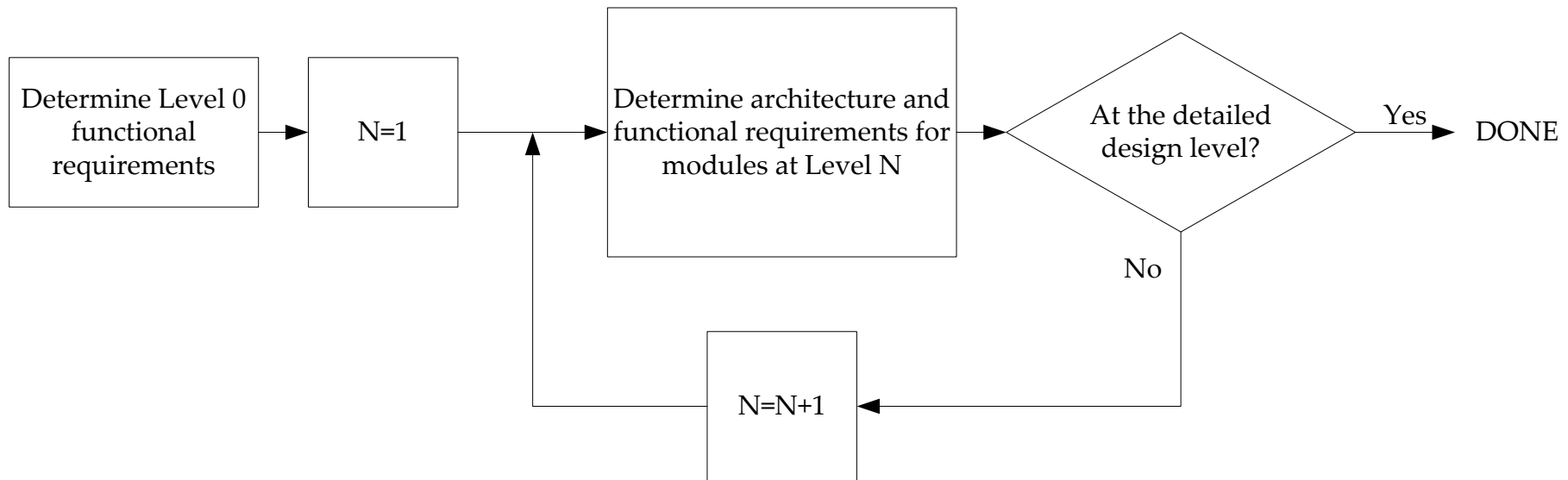
Top Down

- ▶ Given the specification of a system
- ▶ Develop a working system
 - Divide the problem into abstract modules
 - Reiterate until constituent parts are reached
- ▶ Pros
 - Highly predictable design cycle
 - Efficient division of labor
- ▶ Cons
 - More time spent in planning
 - May limit innovation

5.2 Functional Decomposition

Recursively divide and conquer (top down)

- Split a module into several submodules
- Define the input, output, and behavior
- Stop when you reach realizable components



5.3 Guidance

1. The design process is **iterative**
2. Upfront time saves redesign time later
3. Submodules should have similar complexity
4. Precise input, output, and behavior specifications
5. Look for innovation
6. Don't decompose *ad infinitum*

Guidance, continued

7. Use suitable abstraction to describe submodules
8. Look at how it has been done before
9. Use existing technology
10. Keep it simple
11. Communicate results

5.4 Application: Audio Power Amplifier

The system must

- ▶ Accept an audio input signal source with a maximum input voltage of 0.5V peak.
- ▶ Have adjustable volume control between zero volume and the maximum volume level.
- ▶ Deliver a maximum of 50W to an 8Ω speaker.
- ▶ Be powered by a standard 120V 60Hz AC outlet.

Level 0

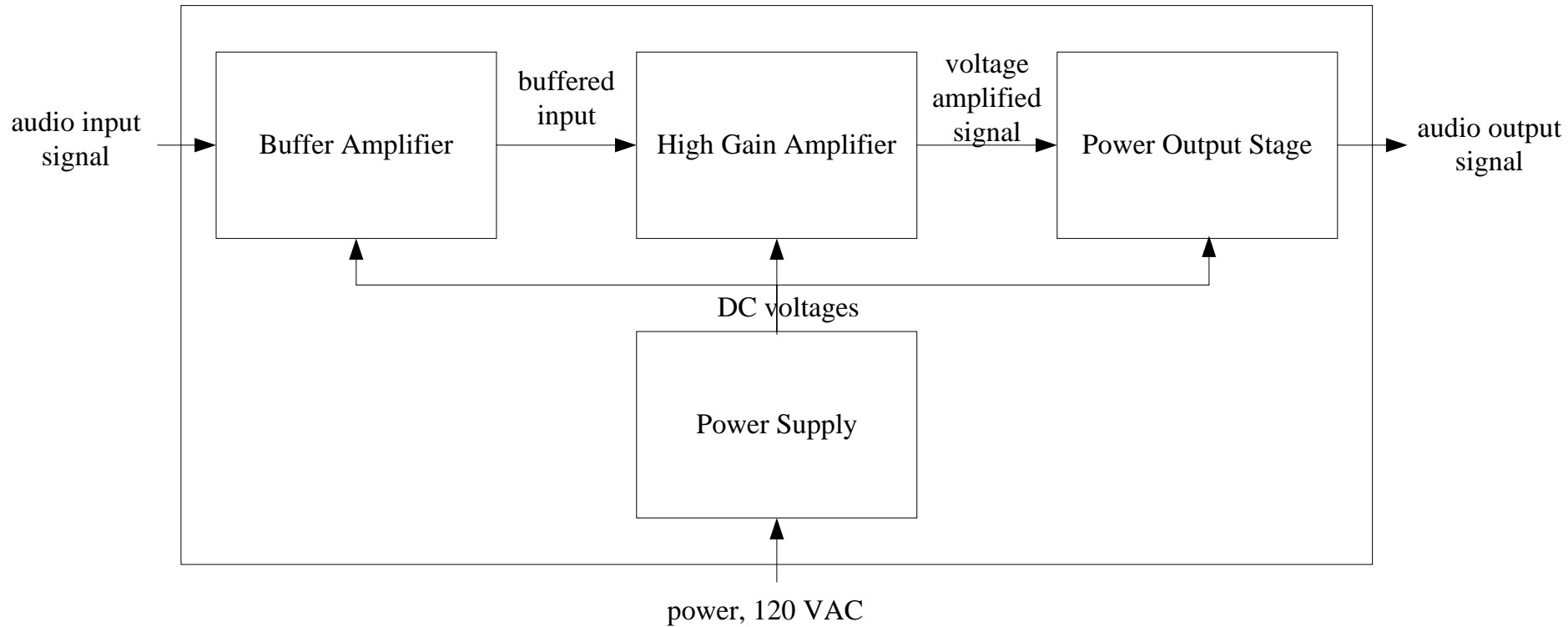
Module	Audio Power Amplifier
Inputs	Audio input signal: 0.5V peak. Power: 120 volts AC rms, 60Hz. User volume control: variable control.
Outputs	Audio output signal: $\underline{?}$ V peak value.
Functionality	Amplify the input signal to produce a 50W maximum output signal. The amplification should have variable user control. The output volume should be variable between no volume and a maximum volume level.



Level 1



Audio Amplifier Design



Level 1 – Buffer amp

Module	Buffer Amplifier
Inputs	<ul style="list-style-type: none"> - Audio input signal: 0.5V peak. - Power: \pm <u>25V</u> DC.
Outputs	<ul style="list-style-type: none"> - Audio signal: 0.5V peak.
Functionality	Buffer the input signal and provide unity voltage gain. It should have an input resistance $>$ <u>1MΩ</u> and an output resistance $<$ <u>100Ω</u> .

Level 1 – High gain amp



<i>Module</i>	High Gain Amplifier
<i>Inputs</i>	<ul style="list-style-type: none">- Audio input signal: 0.5V peak.- User volume control: variable control.- Power: \pm <u>25V</u> DC
<i>Outputs</i>	<ul style="list-style-type: none">- Audio signal: <u>20V</u> peak.
<i>Functionality</i>	Provide an adjustable voltage gain, between <u>1</u> and <u>40</u> . It should have an input resistance $>$ <u>100kΩ</u> and an output resistance $<$ <u>100Ω</u> .

Application Domains

- ▶ Electronics Design
- ▶ Digital Design
- ▶ Software Design
- ▶ See the book for more in-depth examples

5.7 Example: Thermometer Design

The system must

- ▶ Measure temperature between 0 and 200°C.
- ▶ Have an accuracy of 0.4% of full scale.
- ▶ Display the temperature digitally, including one digit beyond the decimal point.
- ▶ Be powered by a standard 120V 60Hz AC outlet.
- ▶ Use an RTD (thermal resistive device) that has an accuracy of 0.55°C over the range. The resistance of the RTD varies linearly with temperature from 100Ω at 0°C to 178Ω at 200°C.

Level 0

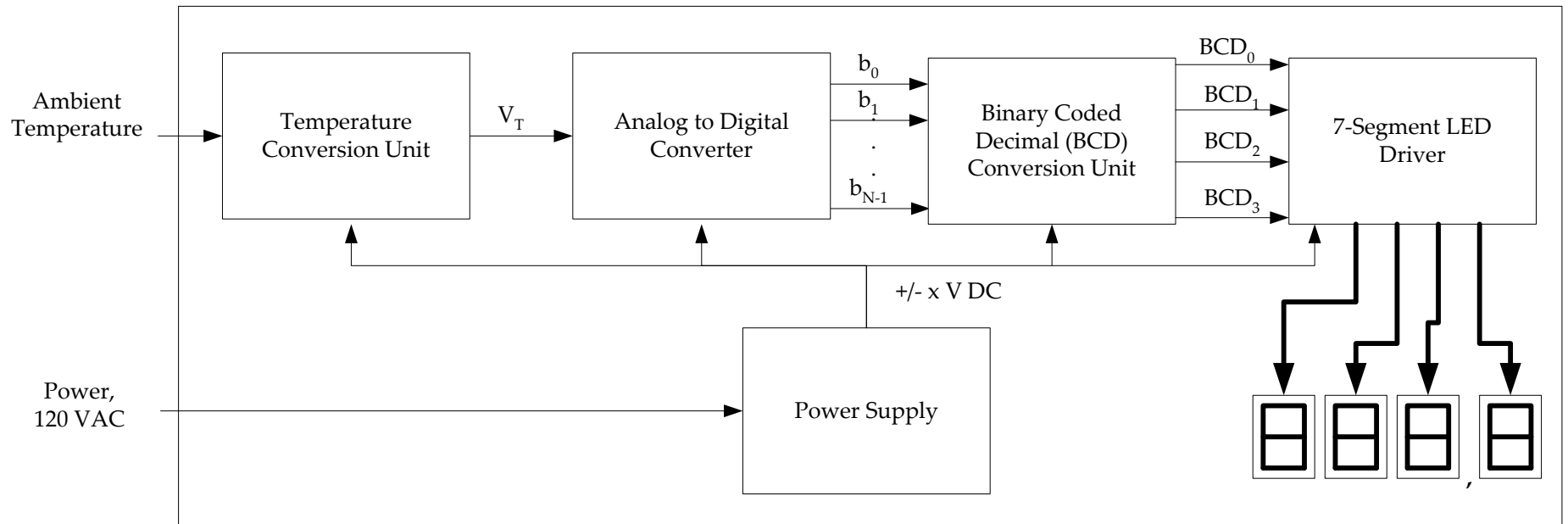


Level 0



<i>Module</i>	Digital Thermometer
<i>Inputs</i>	<ul style="list-style-type: none">- Ambient temperature: 0-200°C.- Power: 120V AC power.
<i>Outputs</i>	<ul style="list-style-type: none">- Digital temperature display: A four digit display, including one digit beyond the decimal point.
<i>Functionality</i>	Displays temperature on digital readout with an accuracy of 0.4% of full scale.

Level 1



Level 1

<i>Module</i>	Temperature Conversion Unit
<i>Inputs</i>	<ul style="list-style-type: none"> - Ambient temperature: 0-200°C. - Power: $\underline{\quad}$V DC (to power the electronics).
<i>Outputs</i>	<ul style="list-style-type: none"> - V_T: temperature proportional voltage. $V_T = \underline{\alpha}T$, and ranges from $\underline{\quad}$ to $\underline{\quad}$V.
<i>Functionality</i>	Produces an output voltage that is linearly proportional to temperature. It must achieve an accuracy of $\underline{\quad}$ %.

Level 1



<i>Module</i>	A/D Converter
<i>Inputs</i>	<ul style="list-style-type: none">- V_T: voltage proportional to temperature that ranges from $\underline{?}$ to $\underline{?}$V.- Power: $\underline{?}$V DC.
<i>Outputs</i>	<ul style="list-style-type: none">- $b_{N-1} - b_0$: $\underline{?}$-bit binary representation of V_T.
<i>Functionality</i>	Converts analog input to binary digital output.

Design Details

- ▶ How would you determine the unknown details in the previous 2 slides?

5.8 Coupling and Cohesion

- ▶ What is coupling?
- ▶ How much coupling is there in the modules in the Level 1 of the previous amplifier example?
- ▶ Phenomena of highly coupled systems
 - A failure in 1 module propagates
 - Difficult to redesign 1 module
- ▶ Phenomena of low coupled systems
 - Discourages reutilization of a module

Cohesion

- ▶ What is cohesion?
- ▶ Phenomena of highly cohesive systems
 - Easy to test modules independently
 - Simple (non-existent) control interface
- ▶ Phenomena of low cohesive systems
 - Less reuse of modules

5.9 Project Application: The Functional Design

- ▶ **Design Level 0**
 - Present a single module block diagram with inputs and outputs identified.
 - Present the functional requirements: inputs, outputs, and functionality.
- ▶ **Design Level 1**
 - Present the Level 1 diagram (system architecture) with all modules and interconnections shown.
 - Describe the theory of operation. This should explain how the modules work together to achieve the functional objectives.
 - Present the functional requirements for each module at this level.
- ▶ **Design Level N (for $N > 1$)**
 - Repeat the process from design Level 1 as necessary.
- ▶ **Design Alternatives**
 - Describe the different alternatives that were considered, the tradeoffs, and the rationale for the choices made. This should be based upon concept evaluation methods in Chapter 4.

5.10 Summary

- ▶ Design approach: top-down and bottom-up
- ▶ Functional Decomposition
 - Iterative decomposition
 - Input, output, and function
 - Applicable to many problem domains
- ▶ Coupling – interconnectedness of modules
- ▶ Cohesion – focus of modules